FINE PARTICLES OF OXIDE CRYSTAL AND SLURRY FOR POLISHING WHICH CONTAINS THE FINE PARTICLES

ABSTRACT

To provide a slurry for polishing which is excellent in polishing properties, can suppress scratches and is appropriate for accurate polishing in semiconductor production steps, and fine particles of oxide crystal for it.

Fine particles of oxide crystal, characterized in that the ratio of the crystallite size measured by X-ray diffraction method and calculated by Scherrer method to the average primary particle size equivalent to sphere from the specific surface area measured by BET is the crystallite size:the average primary particle size = 1:0.8 to 1:2.5. A slurry for polishing, characterized in that the fine particles of oxide crystal are dispersed in a liquid medium, and from 0.1 to 40 mass% of the fine particles of oxide crystal are contained, per the total mass of the slurry for polishing.

Fig. 1